Abstract

This invention relates to a device for especially temporary bonding of a first substrate (15) with a second substrate with the following features:

- a mounting apparatus for mounting of the first substrate (15) on a mounting contour (8, 8', 8", 8"', 8^{IV}) with an active mounting surface (7, 7', 7", 7"', 7^{IV}) of the mounting apparatus with an outer ring section (10) for controllable fixing of the first substrate (15),

- deformation means for controllable deformation of the first substrate (15), the deformation means being made to act within the outer ring section and

- bonding means for bonding of the first substrate (15) with the second substrate (15).

Furthermore the invention relates to a method for especially temporary bonding of a first substrate (15) to a second substrate with the following steps, especially the following sequence:

- mounting the first substrate (15) on a mounting contour (8, 8', 8", 8"', 8^{IV}) with an active mounting surface (7, 7', 7", 7"', 7^{IV}) of the mounting apparatus (1) with an outer ring section (10) for controllable fixing of the first substrate (15),

- deforming the first substrate (15) within the outer ring section by deformation means for controllable deformation of the first substrate (15)

- bonding of the first substrate (15) with the second substrate by bonding means.

Figure 5a